



	0																



Fig.1 Forward Current Derating Curve

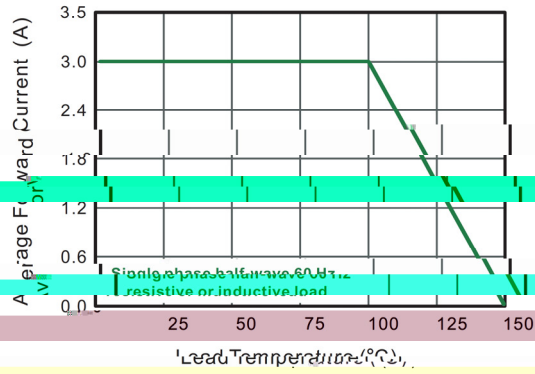


Fig.2 Typical Reverse Characteristics

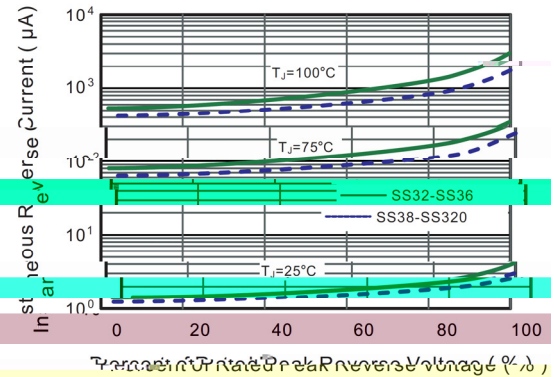


Fig.3 Typical Forward Characteristic

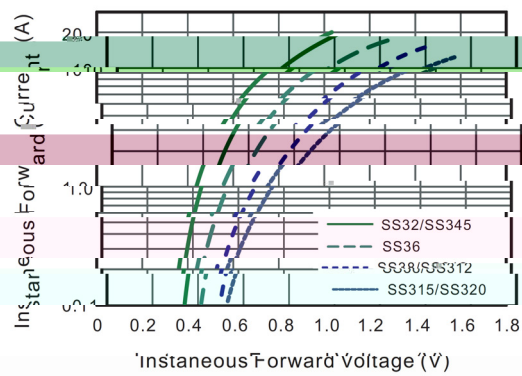


Fig.4 Typical Junction Capacitance

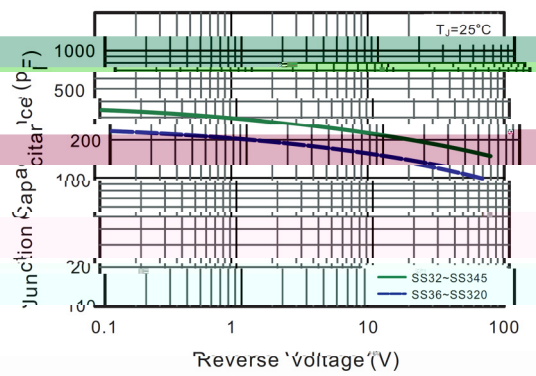


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

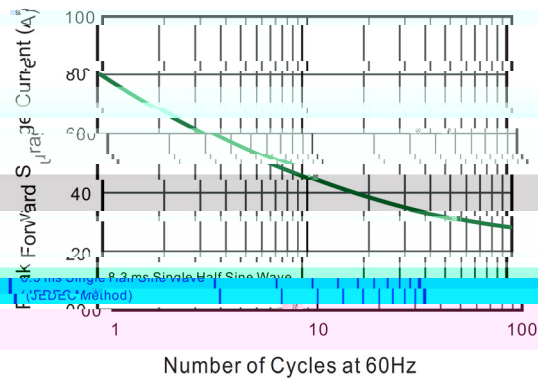
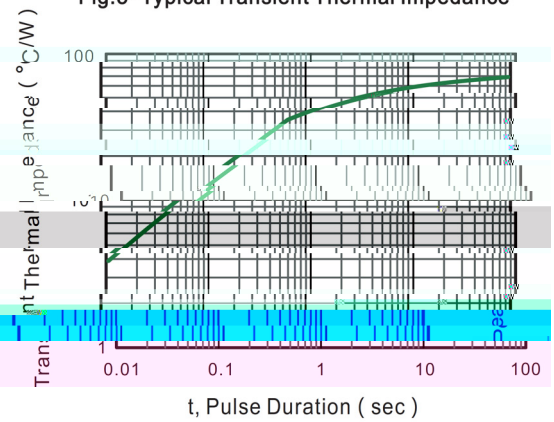
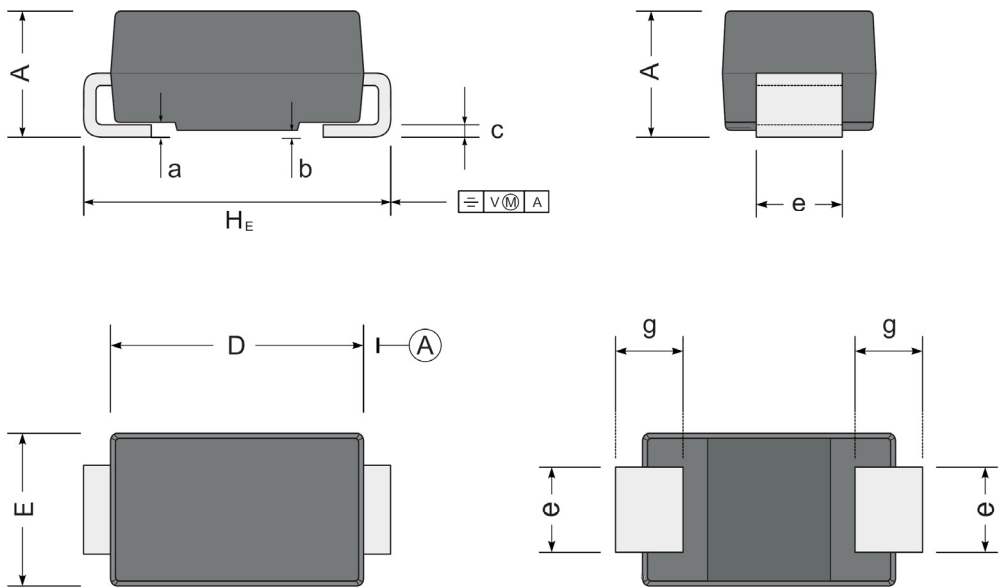


Fig.5- Typical Transient Thermal Impedance





UNIT		A	D	E	H _E	c	e	g	b	a
mm	max	2.2	4.5	2.7	5.2	0.31	1.6	1.5	0.2	0.3
	min	1.9	4.0	2.3	4.7	0.15	1.3	0.9	0.05	
mil	max	87	181	106	205	12	63	59	7.9	12
	min	75	157	91	185	6	51	35	2	

[illegible]

Temperature Profile for IR Reflow Soldering(Pb-Free)

封装形式

Units/Reel
只/卷盘

Reels/Inner Box
卷盘/盒

Units/Inner Box
只/盒

Inner Boxes/Outer Box
盒/箱

Units/Outer Box
只/箱

Reel

Inner Box 盒

Outer Box 箱